

## ELECTRONIC DEVICES TEST 4

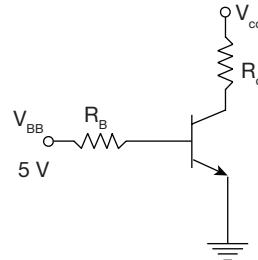
**Number of Questions: 25**

**Time: 60 min.**

**Directions for questions 1 to 25:** Select the correct alternative from the given choices.

1. Silicon dioxide ( $\text{SiO}_2$ ) is used in ICs
  - (A) because it facilitates the penetration of diffusants.
  - (B) to control the location of diffusion and to protect and insulate the silicon surface.
  - (C) because of its high heat conduction
  - (D) to control the concentration of diffusants.
2. In an n channel MOSFET  $I_{D(\text{sat})} = 0.3 \text{ mA}$   
 $V_{DS} = 0.9 \text{ V}$ ,  $V_{Th} = 0.8 \text{ V}$  and  $V_{DS(\text{sat})} = 4 \text{ V}$ .  
 The gate voltage is
  - (A) 3.8 V
  - (B) 4.2 V
  - (C) 4.8 V
  - (D) 3.2 V
3. A MOS capacitor has oxide thickness  $t_{ox}$  of 70 nm. The capacitance is
  - (A)  $0.49 \text{ mF/m}^2$
  - (B)  $0.49 \mu\text{F/m}^2$
  - (C)  $0.39 \text{ mF/m}^2$
  - (D)  $0.39 \mu\text{F/m}^2$
4. In a n channel enhancement mode MOSFET,  $V_{Th} = 1.6 \text{ V}$ ,  $K_n = 0.28 \text{ mA/V}^2$ .  
 If  $V_{GS} = 5 \text{ V}$  and  $V_{DS} = 6 \text{ V}$  then  $I_D$  is
  - (A) 2.34 mA
  - (B) 1.36  $\mu\text{A}$
  - (C) 2.36  $\mu\text{A}$
  - (D) 0.672 mA
5. Compared to junction isolation, oxide isolation is
  - (A) better because it causes less disruption in the Si crystalline structure.
  - (B) worse because it eliminates conducting paths needed for current flow into the substrate.
  - (C) better because it eliminates parasitic junction capacitances.
  - (D) None of these
6. Silicon dioxide layer is used in IC chips for
  - (A) providing contacts
  - (B) diffusing elements
  - (C) providing mechanical strength to the chip
  - (D) providing mask against diffusion
7. A JFET has  $I_{DSS} = 18 \text{ mA}$  and  $V_p = -6 \text{ volts}$ ,  $V_{GS} = -2 \text{ V}$  the value of drain current is
  - (A) 4 mA
  - (B) 6 mA
  - (C) 7.9 mA
  - (D) 8.3 mA
8. The threshold voltage of an n channel MOSFET can be increased by
  - (A) reducing channel dopant concentration
  - (B) reducing the channel length
  - (C) increasing the channel dopant concentration
  - (D) reducing the gate oxide thickness.
9. A JFET has  $V_p = -8.5 \text{ V}$ ,  $I_{DSS} = 20 \text{ mA}$  and  $I_D = 3.5 \text{ mA}$  determine its transconductance
  - (A) 2.22  $\text{mA/V}$
  - (B) 1.99  $\text{mA/V}$
  - (C) 3.6  $\text{mA/V}$
  - (D) 4.2  $\text{mA/V}$

- 10.** Consider the transistor circuit shown in figure



If the Base current  $I_B = 3 \text{ mA}$ , then the value of  $R_B$  would be \_\_\_\_\_.

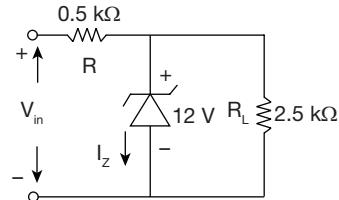
(Consider  $V_{BE} = 0.7 \text{ V}$  and ' $\alpha$ ' = 0.985)

- (A)  $1.7 \text{ k}\Omega$
- (B)  $1.66 \text{ k}\Omega$
- (C)  $1.9 \text{ k}\Omega$
- (D)  $1.43 \text{ k}\Omega$

- 11.** Purpose of metallization in IC fabrication process is

- (A) to act as a heat sink
- (B) to supply a bonding surface for mounting the chip.
- (C) to interconnect the various circuit elements
- (D) to protect the chip from oxidation.

- 12.** For the zener voltage regulator shown in the figure



If the maximum zener current does not exceeds 25 mA. Then the ratio between the  $V_{in \text{ max}}$  to  $V_{in \text{ min}}$  is \_\_\_\_\_.

- (A) 1.64
- (B) 2
- (C) 1.52
- (D) 2.2

- 13.** Calculate the resistance of a diffused resistor that is 45  $\mu\text{m}$  long and 10  $\mu\text{m}$  wide. A 80  $\mu\text{m}$  thick Si wafer has been doped uniformly with boron of the concentration  $10^{16} \text{ cm}^3$ .

- (A)  $7.3 \Omega$
- (B)  $82 \Omega$
- (C)  $820 \Omega$
- (D)  $703 \Omega$

- 14.** A thin film capacitor has a silicon dioxide thickness of 18  $\text{\AA}$ . If the relative dielectric constant of  $\text{SiO}_2$  is 3.9. Calculate the capacitance per unit Area in  $\mu\text{F/cm}^2$ .

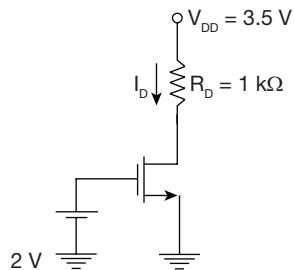
- (A) 1.73
- (B) 1.91
- (C) 0.78
- (D) 2.32

- 15.** For an n-channel silicon FET with  $a = 3 \times 10^4 \text{ cm}^{-2}$  and  $N_D = 10^{17} \text{ electrons/cm}^3$ . The pinch off voltage  $V_p$  is \_\_\_\_\_.

- (Consider  $\epsilon_s = \epsilon_0 \epsilon_r = 12 \epsilon_0$ ).
- (A) 6.77 V
  - (B) 6.23 V
  - (C) 5.2 V
  - (D) 4.7 V

16. Consider the MOSFET circuit shown in figure it has

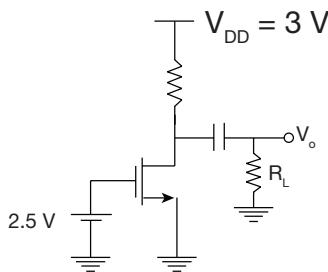
$$V_T = 1\text{ V}, \text{ and } \mu_n C_{ox} \left( \frac{W}{L} \right) = 1.5 \text{ mA/V}^2.$$



The drain current  $I_D$  will be \_\_\_\_\_  
 (A) 0.52 mA      (B) 1.25 mA  
 (C) 1.5 mA      (D) 0.75 mA

17. An NMOS transistor has  $V_{to} = 1\text{ V}$ ,  $2\Phi_f = 0.7\text{ V}$ , and the fabrication process parameter  $\gamma = 0.4\text{ V}^{1/2}$ . The value of threshold voltage ( $V_t$ ), when  $V_B = 3.3\text{ V}$  is \_\_\_\_\_.  
 (A) 1.46 V      (B) 1.32 V  
 (C) 1.21 V      (D) 0.782 V

18. Consider the n-channel MOSFET circuit shown in figure. It has  $V_t = 1.5\text{ V}$ ,  $K_n^1 \frac{W}{L} = 0.25 \text{ mA/V}^2$ , and  $V_A = 50\text{ V}$ .



The output resistance  $r_o$  is \_\_\_\_\_  
 (A) 57 kΩ      (B) 400 kΩ  
 (C) 200 kΩ      (D) 125 kΩ

19. A 1.8 kΩ resistor has to be fabricated using an *n*-type silicon bar with 5 mm thick, 40 μm wide and 400 μm long, the required donor concentration is \_\_\_\_\_ atoms/m<sup>3</sup>.

$$(\mu_n = 1300 \text{ cm}^2/\text{V.sec})$$

$$(A) 5.34 \times 10^{19} \quad (B) 6.5 \times 10^{22} \\ (C) 1.6 \times 10^{23} \quad (D) 5.3 \times 10^{21}$$

20. A doped silicon semiconductor square bar with resistivity  $250 \text{ k}\Omega\text{-cm}$  is placed in transverse magnetic field of  $0.5 \text{ wb/m}^2$  and width = 8 mm. The hall voltage and current measured are  $55 \text{ mV}$  and  $8 \mu\text{A}$  respectively. Find the mobility of carriers.

$$(A) 1400 \text{ cm}^2/\text{V.sec} \quad (B) 1800 \text{ cm}^2/\text{V.sec} \\ (C) 440 \text{ cm}^2/\text{V.sec} \quad (D) 350 \text{ cm}^2/\text{V.sec}$$

21. Silicon is doped with acceptor concentration of  $5 \times 10^{14} \text{ atom/cm}^3$ . Assume the intrinsic carrier concentration of silicon to be  $1.2 \times 10^{10} \text{ cm}^{-3}$  at  $V_t = 28 \text{ mV}$ . Compared to intrinsic silicon, the shift in position Fermi level of extrinsic silicon is

$$(A) 0.325 \text{ eV} \quad (B) 0.297 \text{ eV} \\ (C) 0.423 \text{ eV} \quad (D) 0.79 \text{ eV}$$

22. For a silicon *P-N*junction diode, the doping concentrations are  $N_A = 10^{18} \text{ cm}^3$ ,  $N_D = 10^{19} \text{ cm}^3$ ,  $n_i = 1.5 \times 10^{15} \text{ cm}^3$ . If the cross sectional area of junction is  $10 \text{ mm}^2$ , and junction is reverse biased at  $6.5\text{V}$  find the transition capacitance.

$$(\epsilon_r = 12, \epsilon_0 = 8.85 \times 10^{-12} \text{ F/m}) \\ (A) 0.2 \text{ nF} \quad (B) 0.1 \text{ pF} \\ (C) 0.1 \text{ nF} \quad (D) 0.2 \text{ pF}$$

23. A silicon diode operates at forward bias voltage of  $0.7\text{V}$ , ( $\eta = 2$  for silicon) calculate the factor by which the current get multiplied when the temperature is increased from  $27^\circ$  to  $107^\circ\text{C}$ .

$$(A) 19 \quad (B) 17.2 \\ (C) 715.4 \quad (D) 256$$

24. A diode with forward bias voltage of  $0.695 \text{ volts}$  is carrying  $1.95 \text{ mA}$  of current at room temperature. If  $\eta = 1$ , for this diode, the dynamic resistance of the diode is?

$$(A) 356 \Omega \quad (B) 13.3 \Omega \\ (C) 26.6 \Omega \quad (D) 712 \Omega$$

25. In an asymmetrical silicon diode, the mean life time of holes is  $12 \text{ ns}$  at room temperature, and  $\eta = 2$ . If the forward current of  $0.2 \text{ mA}$  is flowing in the diode, find the diffusion capacitance.

$$(A) 38.5 \text{ pF} \quad (B) 42.5 \mu\text{F} \\ (C) 46.15 \mu\text{F} \quad (D) 52.25 \text{ pF}$$

### ANSWER KEYS

- |       |       |       |       |       |       |       |       |       |       |
|-------|-------|-------|-------|-------|-------|-------|-------|-------|-------|
| 1. B  | 2. C  | 3. A  | 4. D  | 5. C  | 6. D  | 7. C  | 8. A  | 9. B  | 10. D |
| 11. C | 12. A | 13. D | 14. B | 15. A | 16. D | 17. A | 18. B | 19. A | 20. C |
| 21. B | 22. C | 23. A | 24. B | 25. C |       |       |       |       |       |

HINTS AND EXPLANATIONS

1. Choice (B)

$$2. V_{DS(\text{sat})} = V_{GS} - V_{Tn}$$

$$4 = V_{GS} - 0.8$$

$$V_{GS} = 4.8 \text{ V.}$$

Choice (C)

$$3. t_{ox} = \frac{\varepsilon}{C_{ox}} = \varepsilon_{ox} = 3.9 \cdot \varepsilon_0$$

$$C_{ox} = \frac{3.9 \times 8.85 \times 10^{-12}}{70 \times 10^{-9}} = 0.49 \text{ mF/m}^2.$$

Choice (A)

$$4. V_{DS(\text{sat})} = V_{GS} - V_{Tn} = 5 - 1.6 = 3.4 \text{ V}$$

$V_{DS} < V_{DS(\text{sat})}$ , biased in non saturation region.

$$I_D = \frac{K_n}{2} [2(V_{GS} - V_{Tn})V_{DS} - V_{DS}^2]$$

$$= [2(5 - 1.6)6 - 6^2] = 0.672 \text{ mA.}$$

Choice (D)

5. Choice (C)

6. Choice (D)

$$7. I_D = I_{DSS} \left[ 1 - \frac{V_{GS}}{V_P} \right]^2$$

$$= 18 \times 10^{-3} \left[ 1 - \left( \frac{-2}{-6} \right) \right]^2$$

$$= 18 \times 10^{-3} \left[ 1 - \left( \frac{1}{3} \right) \right]^2$$

$$= 18 \times 10^{-3} \times 0.44 = 7.9 \text{ mA}$$

Choice (C)

8. Choice (A)

$$9. g_m = \frac{-2I_{DSS}}{V_P} \left[ 1 - \frac{V_{GS}}{V_P} \right]$$

$$V_{GS} = V_P \left[ 1 - \sqrt{\frac{I_D}{I_{DSS}}} \right]$$

$$= -8.5 \left[ 1 - \sqrt{\frac{3.5}{20}} \right] = -4.911$$

$$g_m = \frac{-2 \times 20mA}{-8.5} \left[ 1 - \frac{-4.9}{-8.5} \right]$$

$$= \frac{40mA}{8.5} = 1.99 \text{ mA/V}$$

Choice (B)

10. Applying KVL to the input loop:

$$V_{BB} - R_B I_B - V_{BE} = 0$$

$$R_B = \frac{V_{BB} - V_{BE}}{I_B} = \frac{5 - 0.7}{3} \text{ k}\Omega$$

$$R_B = 1.433 \text{ k}\Omega$$

Choice (D)

11. Choice (C)

12.  $V = V_L = 12$

$$I_L = \frac{12}{2.5} \text{ mA} = 4.8 \text{ mA}$$

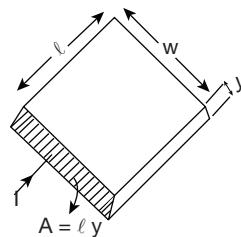
$$\therefore V_{in\ min} = 0.5 \times 10^3 \times 4.8 \times 10^{-3} + 12 \\ = 2.4 + 12 = 16.4 \text{ V}$$

When zener diode current max  $I_R = I_{zm} + I_L$   
 $= 25 \text{ mA} + 4.8 \text{ mA} = 29.8 \text{ mA}$

$$V_{in\ max} = 500 \times 29.8 \times 10^{-3} + 12 = 26.9 \text{ V}$$

$$\frac{V_{in\ max}}{V_{in\ min}} = \frac{26.9}{16.4} = 1.64 \quad \text{Choice (A)}$$

$$13. R = \frac{\rho \ell}{y \cdot w} = R_s \frac{\ell}{w} \Omega$$



$$R = \frac{\ell}{\sigma \cdot y \cdot w} = \frac{\ell}{N_A \mu_p \cdot q \cdot y \cdot w}$$

$$R = \frac{45 \times 10^{-4}}{10^{16} \times 500 \times 1.6 \times 10^{-19} \times 10 \times 10^{-4} \times 80 \times 10^{-4}}$$

$$R = 7.03 \times 10^{-5} \times 10^7 = 703 \Omega$$

Choice (D)

$$14. \text{The capacitance } C = \frac{\varepsilon A}{d}$$

$$\frac{C}{A} = \text{Capacitance per unit area} = \frac{\varepsilon}{d} = \frac{\varepsilon_0 \varepsilon_r}{d}$$

$$= \frac{3.9 \times 8.85 \times 10^{-14}}{18 \times 10^{-8}} \text{ F/cm}^2$$

$$= 1.91 \times 10^{-6} \text{ F/cm}^2 = 1.91 \mu\text{F/cm}^2$$

Choice (B)

$$15. |V_p| = \frac{q \cdot N_D \cdot a^2}{2 \epsilon_s}$$

$$|V_p| = \frac{1.6 \times 10^{-19} \times 10^{17} \times (3 \times 10^{-4})^2}{2 \times 12 \times 8.85 \times 10^{-12}}$$

$$= 0.0677 \times 10^2 = 6.77 \text{ V}$$

Choice (A)

16. From the given data

$$V_G = 2 \text{ V at } V_S = 0$$

$$\therefore V_{GS} = 2 \text{ V}$$

$$V_{DD} = 3.5 \text{ V}, V_T = 1 \text{ V}$$

$$V_{GS} - V_T = 1 \text{ V}$$

So Transistor is in ON state

Let it is in saturation.

$$I_D = \frac{\mu_n C_{ox} w}{2 L} (V_{GS} - V_T)^2$$

$$= \frac{1}{2} \times 1.5 \times 1 \times 10^{-3} = 0.75 \text{ mA}$$

$\therefore V_{GS} > V_T$

Apply KVL at o/p loop:

$$3.5 - I_D R_D - V_{DS} = 0$$

$$3.5 - 0.75 = V_{DS}$$

$$V_{DS} = 2.75 \text{ V}$$

$$\therefore V_{DS} > V_{GS} - V_T$$

So transistor is in saturation mode, so assumption is correct.

Choice (D)

$$\begin{aligned} 17. \quad V_t &= V_{to} + \gamma \left[ \sqrt{2\varphi_f + V_{SB}} - \sqrt{2\varphi_f} \right] \\ &= 1 + 0.4 \left[ \sqrt{0.7 + 3.3} - \sqrt{0.7} \right] = 1 + 0.4[2 - 0.8366] \\ &= 1.465 \text{ volts} \end{aligned}$$

Choice (A)

$$18. \quad \text{We know } r_o = \frac{V_A}{I_D}$$

From the given data

$$V_t = 1.5 \text{ V}, \mu_n C_{ox} \frac{W}{L} = 0.25 \text{ mA/V}^2$$

$$V_{GS} = 2.5 \text{ V}$$

Let us assume transistor is in saturation mode

$$V_{GS} > V_T \rightarrow \text{ON}$$

$$\begin{aligned} I_{Dsat} &= \frac{1}{2} k_n \frac{W}{L} [V_{GS} - V_T]^2 \\ &= \frac{1}{2} \times 0.25 \times 10^{-3} \times 1 = 0.125 \text{ mA} \end{aligned}$$

**Check:-** Saturation mode

Apply KVL in o/p loop.

$$3 - 1.5 \times 0.125 - V_{DS} = 0$$

$$V_{DS} = 2.81825 \text{ V}$$

$$V_{DS} \geq V_{GS} - V_T$$

So it is in saturation mode

$$\therefore \text{O/p resistance } r_o = \frac{50}{0.125} \text{ k}\Omega$$

$$r_o = 400 \text{ k}\Omega$$

Choice (B)

$$19. \quad R = \frac{\rho \ell}{A} = \frac{\ell}{\sigma A}$$

For n type  $\sigma = N_D \cdot q \cdot \mu_n$

$$R = \frac{\ell}{(N_D \cdot q \cdot \mu_n) \times A} \Rightarrow N_D = \frac{\ell}{R \cdot q \cdot \mu_n \times A}$$

$$= \frac{400 \times 10^{-6}}{1.8 \times 10^3 \times 1.6 \times 10^{-19} \times 0.13 \times 5 \times 10^{-3} \times 40 \times 10^{-6}}$$

$$N_D = 5.34 \times 10^{19} \text{ atoms per m}^3$$

Choice (A)

$$20. \quad \text{Mobility } \mu = \sigma \cdot R_H = \frac{R_H}{\rho}$$

$$R_H = \frac{V_H \cdot W}{B_Z \cdot I_x} = \frac{55 \times 10^{-3} \times 8 \times 10^{-3}}{0.5 \times 8 \times 10^{-6}} = 110 \left( \frac{A \cdot \text{sec}}{\text{m}^3} \right)^{-1}$$

$$\mu = \frac{R_H}{\rho} = \frac{110}{2.5 \times 10^3} = 0.044 \text{ m}^2/\text{V.sec}$$

$$= 440 \text{ cm}^2/\text{V.sec}$$

Choice (C)

21. Acceptor concentration =  $5 \times 10^{14}/\text{cm}^2$ , it is a p-type impurity. So Fermi level goes down

$$\text{Shift in Femi level} = \Delta E_F = \frac{KT}{q} \cdot \ln \left( \frac{N_A}{n_i} \right) e_V$$

$$\Delta E_F = 28 \times 10^{-3} \ln \left( \frac{5 \times 10^{14}}{1.2 \times 10^{10}} \right) \text{ eV}$$

= 0.2978 eV

Choice (B)

22.  $N_A = 10^{18} \text{ cm}^{-3}$ ,  $N_D = 10^{19} \text{ cm}^{-3}$ ,  $n_i = 1.5 \times 10^{15} \text{ cm}^{-3}$   
 $A = 10 \text{ mm}^2$  Reverse bias = 6.5V

$$C_T = \frac{\epsilon A}{W}$$

$$W = \left[ \frac{2\epsilon V_i}{q} \left( \frac{1}{N_a} + \frac{1}{N_d} \right) \right]^{\frac{1}{2}} \quad (\because V_j = V + V_o)$$

$$\text{Contact potential } V_o = V_T \ln \left[ \frac{N_a N_d}{n_i^2} \right]$$

$$V_o = 26 \times 10^{-3} \ln \left[ \frac{10^{18} \times 10^{19}}{(1.5 \times 10^{15})^2} \right] = 0.3979 \text{ V}$$

$$V_j = 6.5 + 0.3979 = 6.8979 \text{ V}$$

$$W = \left[ \frac{2 \times \epsilon_o \epsilon_r \times 6.8979}{1.6 \times 10^{-19}} \left( \frac{1}{10^{18}} + \frac{1}{10^{19}} \right) \right]^{\frac{1}{2}} = 1 \times 10^{-5} \text{ cm}$$

$$C_T = \epsilon_r \epsilon_0 A = 1.06 \times 10^{-10} = 0.106 \text{ nF}$$

$$23. \quad I = I_o (e^{V/\eta V_T} - 1)$$

$$V = 0.7, \eta = 2, V_T = \frac{T}{11,600}$$

$$V_T \text{ at } 27^\circ\text{C} = \frac{27 + 273}{11,600} = 0.02586 \text{ V}$$

$$V_T \text{ at } 107^\circ\text{C} = \frac{107 + 273}{11,600} = 0.032758 \text{ V}$$

$$\frac{I_{27}}{I_{107}} = \frac{I_{o(27)}}{I_{o(107)}} \cdot \frac{(e^{0.7/2 \times 0.02586} - 1)}{(e^{0.7/2 \times 0.032758} - 1)}$$

$$\frac{I_{o(27)}}{I_{o(107)}} = 2^{(27-107)/10} = 2^{-8}$$

$$I_{107} = 19.07 I_{27}$$

Choice (A)

24. Dynamic resistance of the diode

$$r = \frac{\eta V_T}{I} = \frac{1 \times 26 \times 10^{-3}}{1.95 \times 10^{-3}} = 13.3 \Omega$$

$$V_T = 26 \text{ mV at room temperature}$$

Choice (B)

25. Diffusion capacitance  $C_D = \frac{\tau I}{\eta V_T} = \frac{12 \times 10^{-9} \times 0.2 \times 10^{-3}}{2 \times 26 \times 10^{-3}}$

$$= 46.15 \mu \text{ F}$$

Choice (C)